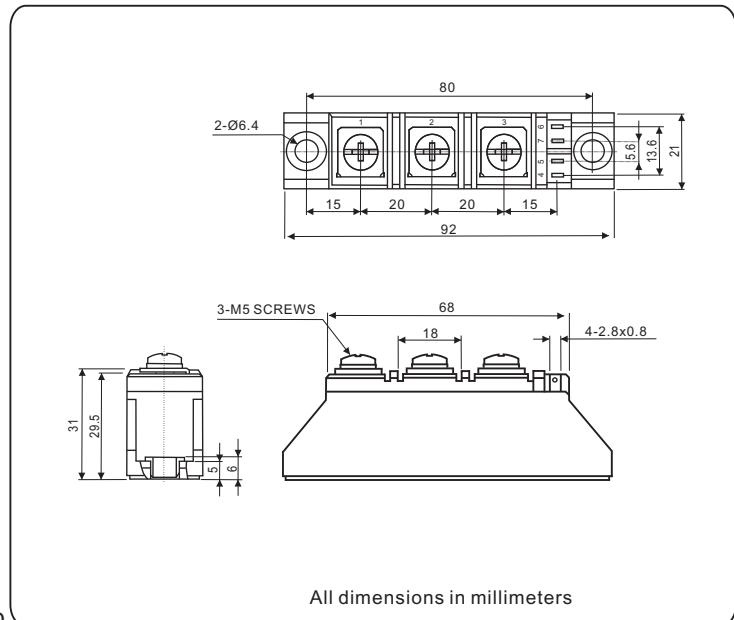


## Thyristor/Diode and Thyristor/Thyristor, 90A (ADD-A-PAK Power Modules)



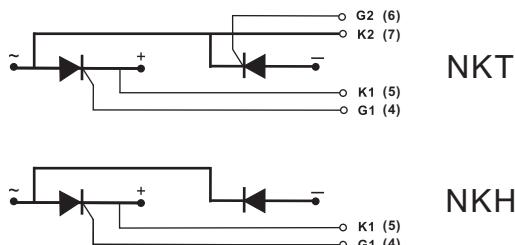
### FEATURES

- High voltage
- Electrically isolated by DBC ceramic ( $\text{Al}_2\text{O}_3$ )
- 3000 V<sub>RMS</sub> isolating voltage
- Industrial standard package
- High surge capability
- Planar SCR chips
- Modules uses high voltage power thyristors/diodes in two basic configurations
- Simple mounting
- UL approved file E320098 
- Compliant to RoHS
- Designed and qualified for multiple level



### APPLICATIONS

- DC motor control and drives
- Battery charges
- Welders
- Power converters
- Lighting control
- Heat and temperature control



### PRODUCT SUMMARY

$I_{T(AV)}$	90 A
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### MAJOR RATINGS AND CHARACTERISTICS

SYMBOL	CHARACTERISTICS	VALUE	UNITS
$I_{T(AV)}$	85 °C	90	A
$I_{T(RMS)}$	85 °C	141	
$I_{FSM}/I_{FSM}$	50 Hz	2000	A
	60 Hz	2100	
$I^2t$	50 Hz	20	$\text{kA}^2\text{s}$
	60 Hz	18.3	
$I^2\sqrt{t}$		200	$\text{kA}^2\sqrt{\text{s}}$
$V_{DRM} / V_{RRM}$	Range	400 to 1600	V
$T_J$	Range	-40 to 125	°C

**ELECTRICAL SPECIFICATIONS**

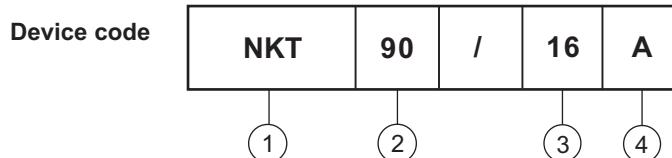
<b>VOLTAGE RATINGS</b>				
<b>TYPE NUMBER</b>	<b>VOLTAGE CODE</b>	<b><math>V_{RRM}/V_{DRM}</math>, MAXIMUM REPETITIVE PEAK REVERSE VOLTAGE V</b>	<b><math>V_{RSM}/V_{DSM}</math>, MAXIMUM NON-REPETITIVE PEAK REVERSE VOLTAGE V</b>	<b><math>I_{RRM}/I_{DRM}</math> AT 125 °C mA</b>
NKT90..A NKH90..A	04	400	500	10
	08	800	900	
	12	1200	1300	
	14	1400	1500	
	16	1600	1700	

<b>FORWARD CONDUCTION</b>								
<b>PARAMETER</b>	<b>SYMBOL</b>	<b>TEST CONDITIONS</b>			<b>VALUE</b>	<b>UNITS</b>		
Maximum average on-state current at case temperature	$I_{T(AV)}$	180° conduction, half sine wave ,50Hz			90	A		
				85	°C			
Maximum RMS on-state current	$I_{T(RMS)}$	180° conduction, half sine wave ,50Hz , $T_C = 85^\circ C$			141	A		
Maximum peak, one-cycle, on-state non-repetitive surge current	$I_{TSM}$	$t = 10 \text{ ms}$	No voltage reapplied	Sine half wave, initial $T_J = T_J$ maximum	2000			
		$t = 8.3 \text{ ms}$			2100			
Maximum $I^2t$ for fusing	$I^2t$	$t = 10 \text{ ms}$	Sine half wave, initial $T_J = T_J$ maximum	100% $V_{RRM}$ reapplied	20	kA <sup>2</sup> s		
		$t = 8.3 \text{ ms}$			18.3			
		$t = 10 \text{ ms}$			14			
		$t = 8.3 \text{ ms}$			12.8			
		$t = 0.1 \text{ ms to } 10 \text{ ms}$			200			
Maximum $I^2\sqrt{t}$ for fusing	$I^2\sqrt{t}$	$t = 0.1 \text{ ms to } 10 \text{ ms}$ , no voltage reapplied			kA <sup>2</sup> \sqrt{s}			
Maximum on-state voltage drop	$V_{TM}$	$I_{TM} = 270A$ , $T_J = 25^\circ C$ , 180° conduction			1.6	V		
Maximum forward voltage drop	$V_{FM}$	$I_{FM} = 270A$ , $T_J = 25^\circ C$ , 180° conduction			1.3			
Maximum holding current	$I_H$	Anode supply = 6 V, resistive load $T_J = 25^\circ C$			150	mA		
Maximum latching current	$I_L$	Anode supply = 6 V resistive load, $T_J = 25^\circ C$			400			

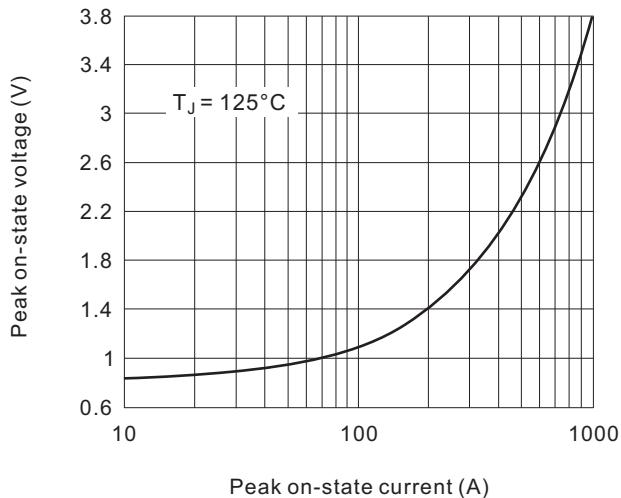
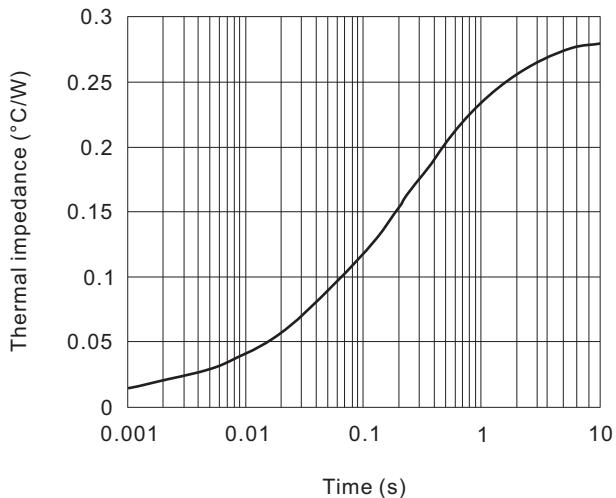
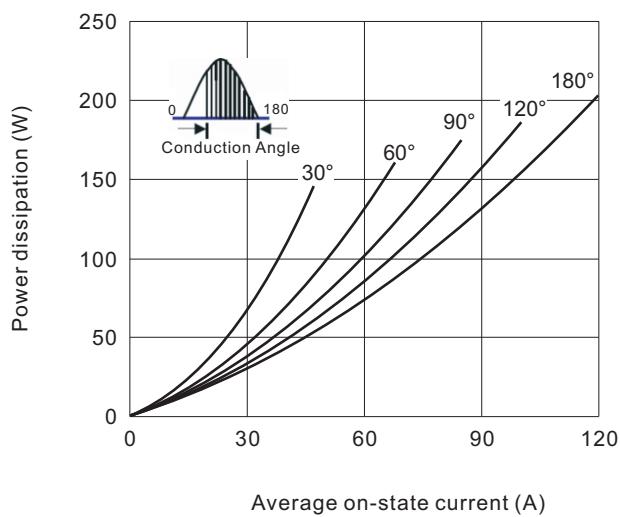
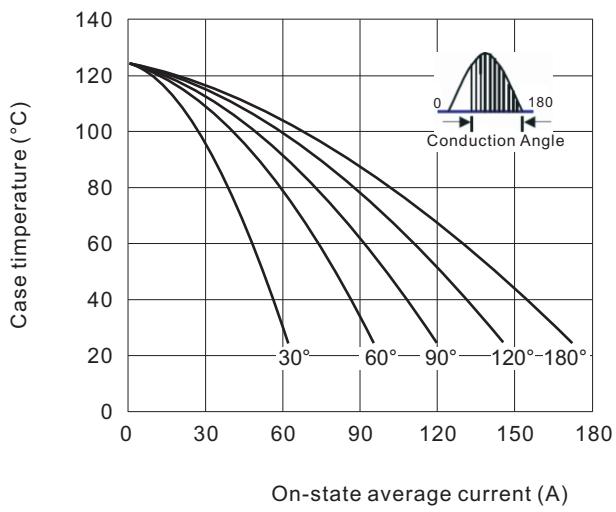
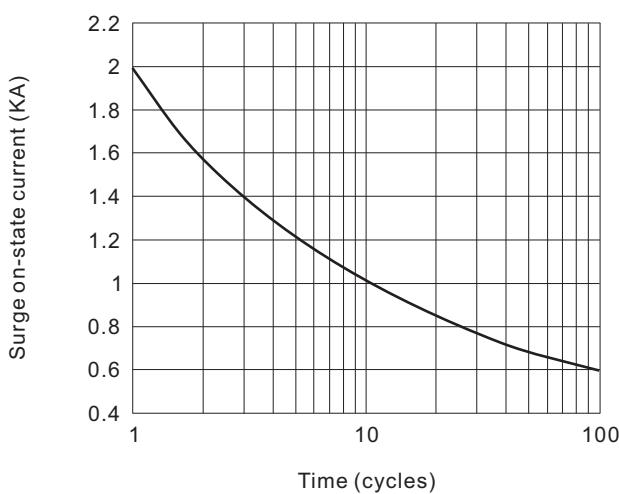
<b>BLOCKING</b>						
<b>PARAMETER</b>	<b>SYMBOL</b>	<b>TEST CONDITIONS</b>			<b>VALUES</b>	<b>UNITS</b>
Maximum peak reverse and off-state leakage current	$I_{RRM}$ $I_{DRM}$	$T_J = 125^\circ C$			10	mA
RMS isolation Voltage	$V_{ISO}$	50 Hz, circuit to base, all terminals shorted			2500 (1min) 3000 (1s)	V
Critical rate of rise of off-state voltage	$dV/dt$	$T_J = T_J$ maximum, exponential to 67 % rated $V_{DRM}$			1000	V/μs

TRIGGERING					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum peak gate power	P <sub>GM</sub>	$t_p \leq 5 \text{ ms}$ , T <sub>J</sub> = T <sub>J</sub> maximum		10	W
Maximum average gate power	P <sub>G(AV)</sub>	$f = 50 \text{ Hz}$ , T <sub>J</sub> = T <sub>J</sub> maximum		3	
Maximum peak gate current	I <sub>GM</sub>	$t_p \leq 5 \text{ ms}$ , T <sub>J</sub> = T <sub>J</sub> maximum		3	A
Maximum peak negative gate voltage	- V <sub>GM</sub>			10	
Maximum required DC gate voltage to trigger	V <sub>GT</sub>	T <sub>J</sub> = 25 °C	Anode supply = 6 V, resistive load; R <sub>a</sub> = 1Ω	0.7~1.6	V
Maximum required DC gate current to trigger	I <sub>GT</sub>			20~100	
Maximum gate voltage that will not trigger	V <sub>GD</sub>	T <sub>J</sub> = T <sub>J</sub> maximum, 66.7% V <sub>DRM</sub> applied		0.25	V
Maximum gate current that will not trigger	I <sub>GD</sub>			10	
Maximum rate of rise of turned-on current	dI/dt	T <sub>J</sub> = 25°C, I <sub>GM</sub> = 1.5A, t <sub>r</sub> ≤ 0.5 μs		150	A/μs

THERMAL AND MECHANICAL SPECIFICATIONS					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum junction operating temperature range	T <sub>J</sub>			- 40 to 125	°C
Maximum storage temperature range	T <sub>Stg</sub>			- 40 to 150	
Maximum thermal resistance, junction to case per junction	R <sub>thJC</sub>	DC operation		0.28	°C/W
Maximum thermal resistance, case to heatsink per module	R <sub>thCS</sub>	Mounting surface, smooth, flat and greased		0.077	
Mounting torque ± 10 % AAP to heatsink, M6 busbar to AAP, M5		A mounting compound is recommended and the torque should be rechecked after a period of 3 hours to allow for the spread of the compound. Lubricated threads.		4	N.m
Approximate weight				120	g
				4.23	oz.
Case style				ADD-A-PAK	

**ORDERING INFORMATION TABLE**


- [1] - Module type: NKT for (Thyristor + Thyristor) module  
NKH for (Thyristor + Diode) module
- [2] - Current rating: I<sub>T(AV)</sub>
- [3] - Voltage code x 100 = V<sub>RRM</sub>
- [4] - Assembly type,"A" for soldering type

**Fig.1 Peak On-state voltage vs. peak On-state current**

**Fig.2 Max. thermal impedance (junction to case) vs. time**

**Fig.3 Power dissipation vs. average on-state current**

**Fig.4 Case temperature vs. average on-state current**

**Fig.5 Surge on-state current vs. cycles**

**Fig.6 Gate characteristics**
